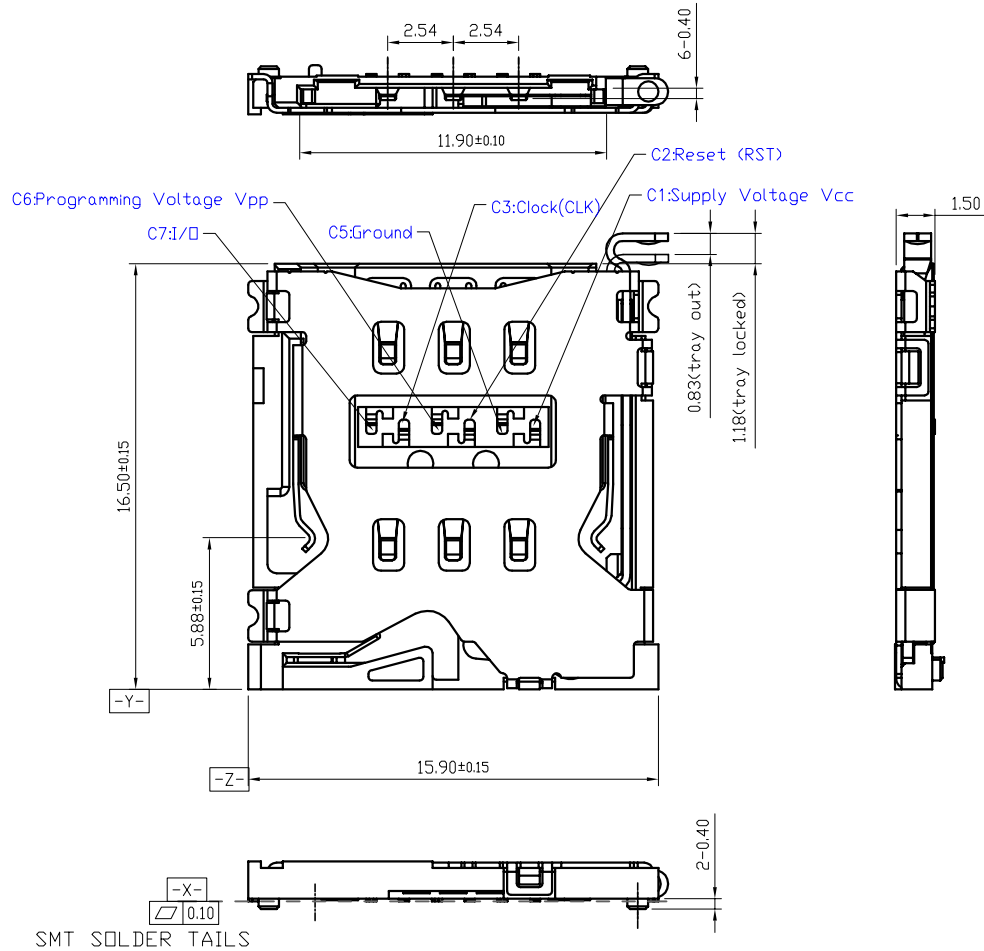
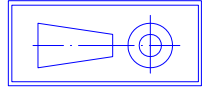


Operation: Thimble Structure & Push Lever (顶针式) NANO-SIM卡座

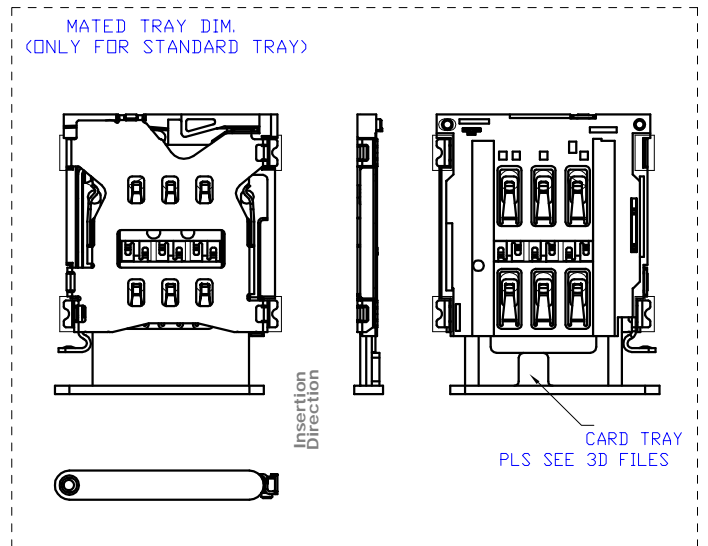
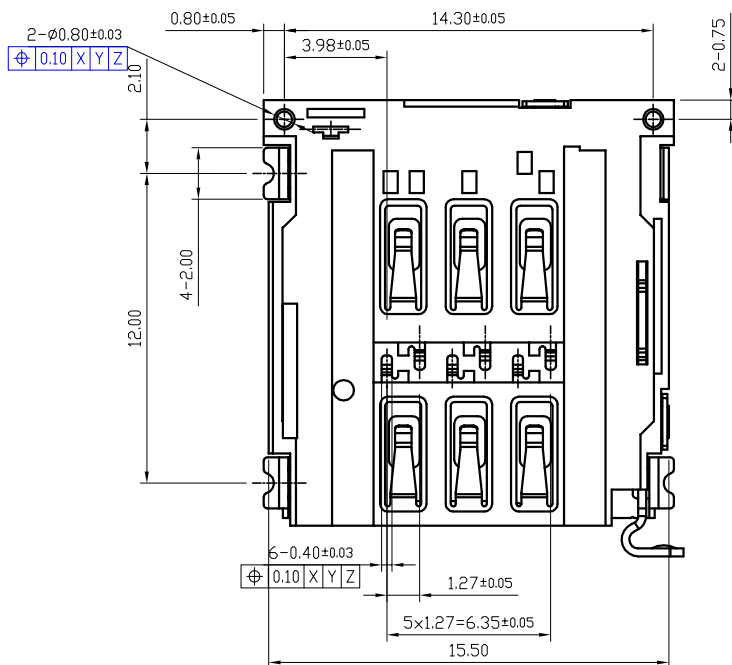


LTEM NO.: SNO-019  
(NANO-SIM CARD SOCKETS)

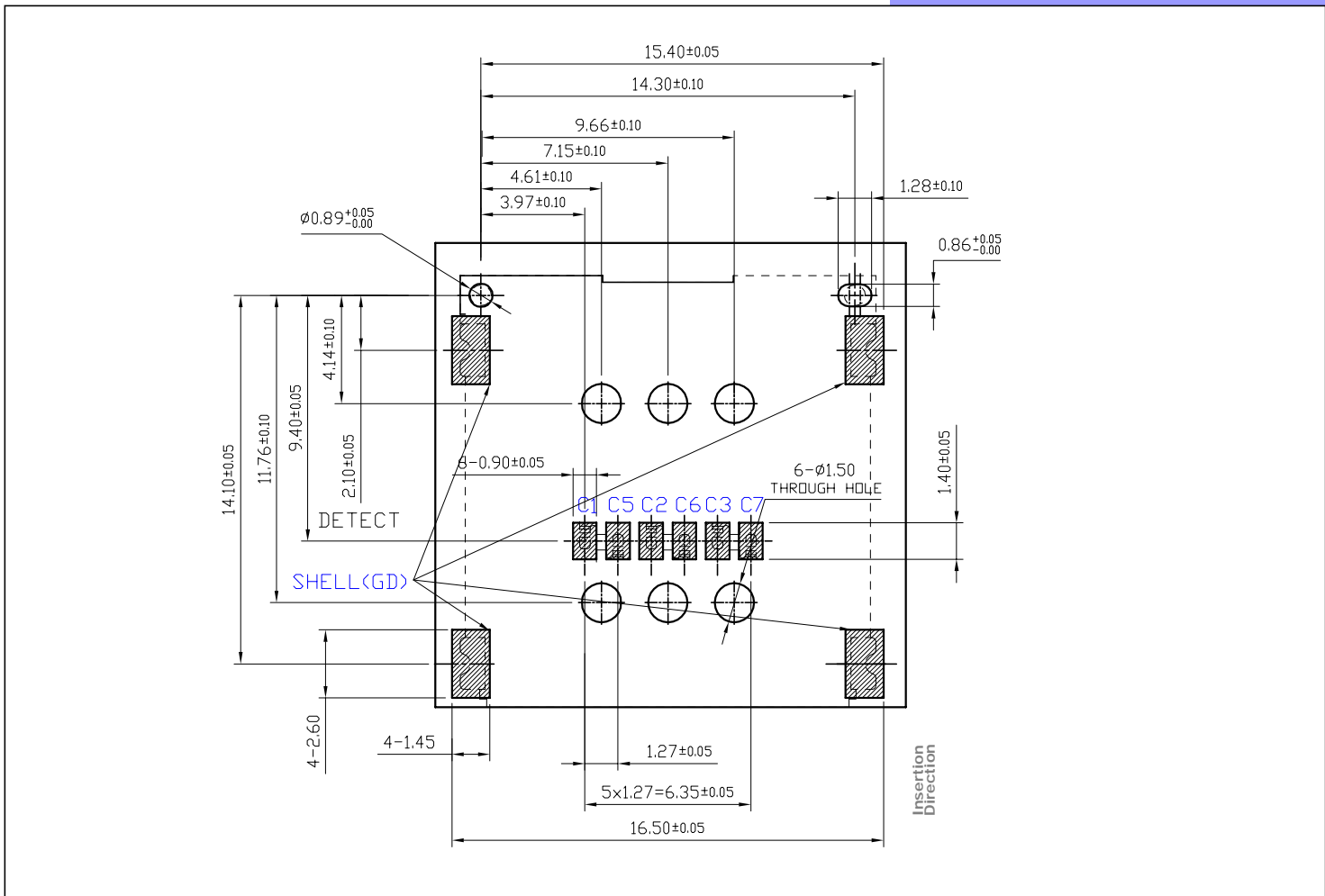
Unit:mm



- 表面貼裝 SMT
- 側向導入 LATERAL
- 精密部品 NICETY
- 可靠 STABILIZE
- 適合環保 RoHS



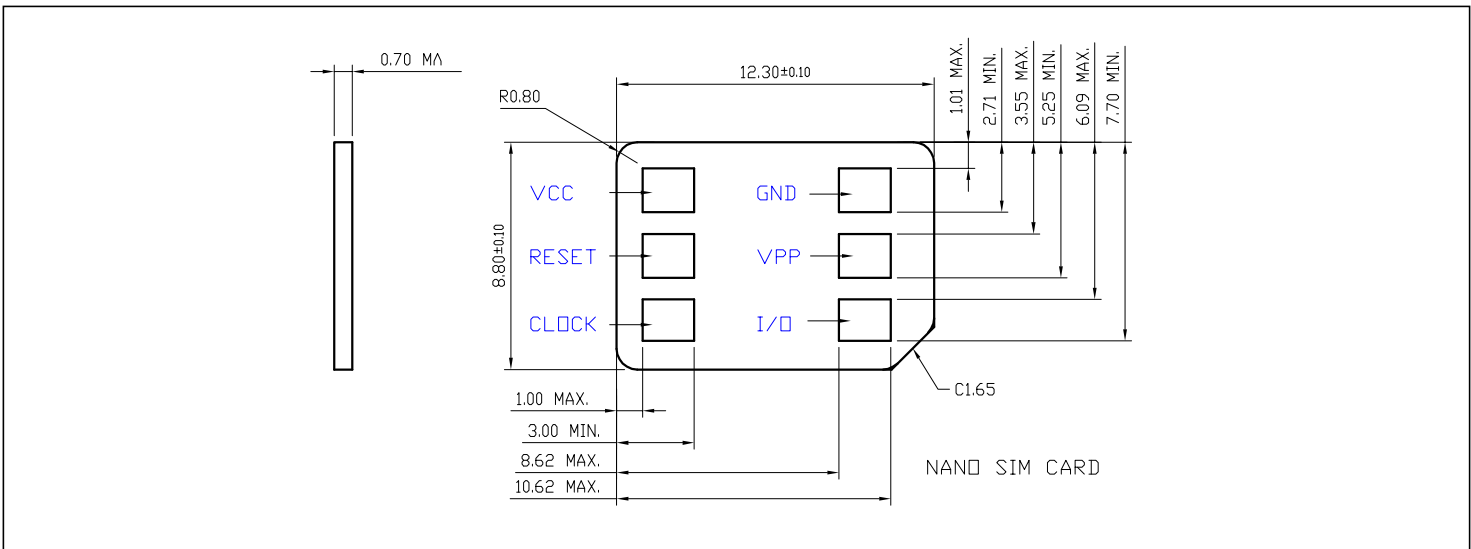
CIRCUIT BOARD SIZE  
(Vertical view)



PIN Assignment

SIM CARD Pin DESIGN

Pin No.	Pin NAME	Type	Description
C①	卡電源	1	VCC
C②	復位	1	RST
C③	時鐘	1	CLK
C④	保留項	1	Reserved
C⑤	接地	1	GND
C⑥	Vpp	1	VPP
C⑦	輸入/輸出	1	I/O
C⑧	保留項	1	Reserved

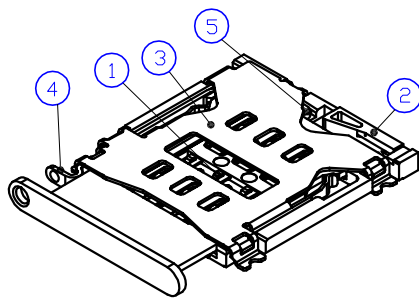


Technical parameter

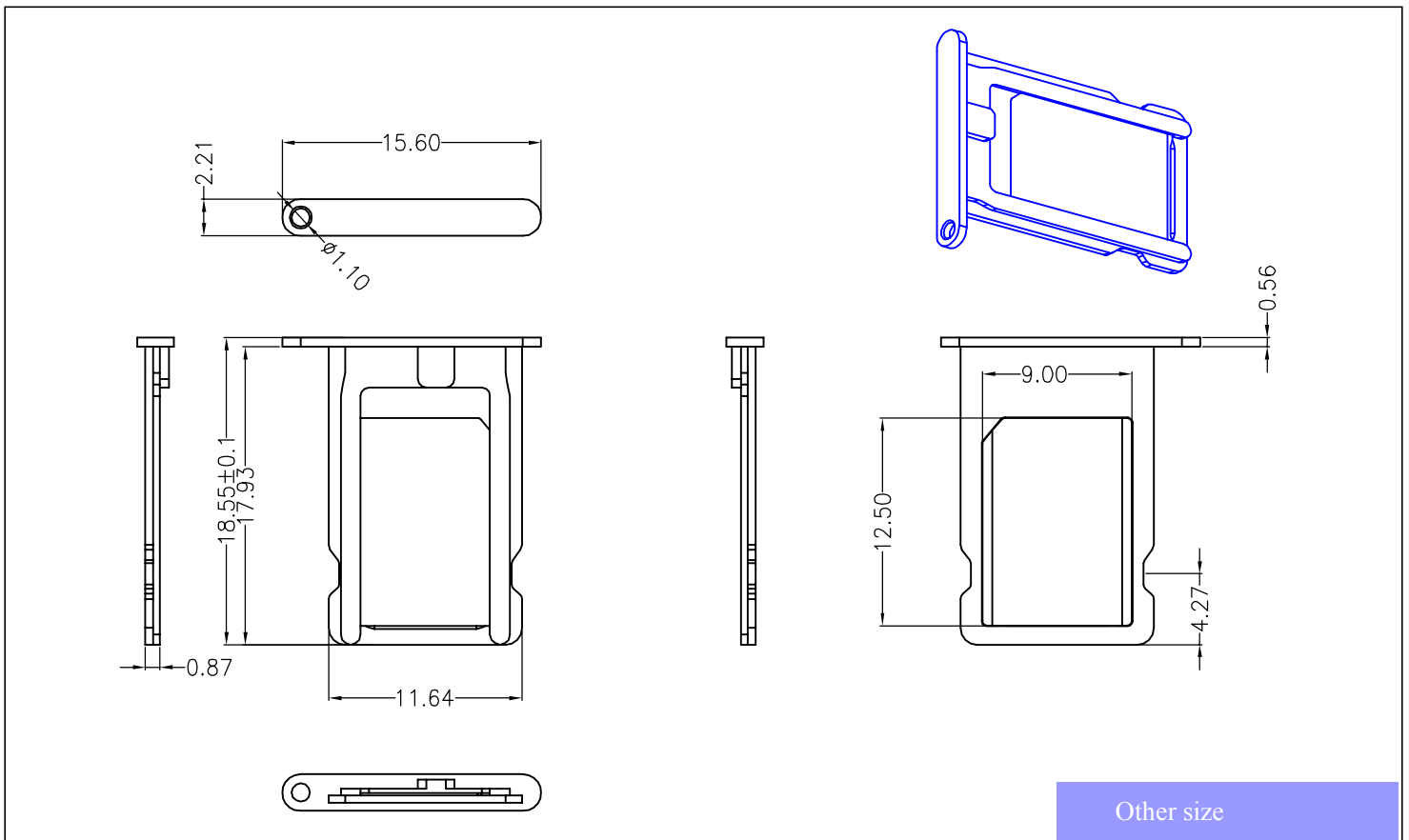
PROJECT		LEVEL	A[better product]	B[average product]	C[low product]
Electrical Properties	Initial Contact Resistance		30mΩ max.	30mΩ max.	no data!
	Contact Resistance		100MΩ min. 100V DC Skey/PD: 50MΩ min. 100V DC		
	Withstand Voltage		300V AC for 1min	250 V AC for 1min	
Durable Performance	There No Load		8,000 Cycles	<b>7,000 Cycles</b>	no data!
	Rated Load		6,500 Cycles 50mΩ max.	<b>5,000 Cycles</b> <b>30mΩ max.</b>	no data!
Insertion Force			4.0Kgf MAX (Springback: )		

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。Products do not belong to hazardous waste,When waste can recycling processing

運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生;運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中[常溫 25°C,濕度在 50°C 以內],不可導致材料變形或氧化。



Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	CONTACT	COPPER ALLOY 【G/F】	0.1 μm Ni PLATED OVERALL; BRONZE ALLOY, GOLD PLATING
② B	HOUSING	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
③ C	SHELL	STAINLESS 【G/F】	SUS304, GOLD PLATING;
④ D	LEVER	STAINLESS 【G/F】	SUS304, NO PLATING;
⑤ E	HINGE	STAINLESS 【G/F】	SUS304, NO PLATING;



Other size

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